

25th Electronics Packaging Technology Conference (EPTC2023)

The Electronics Packaging Technology Conference (EPTC) is an international conference organized by the IEEE Singapore RS/EP/EDS Joint Chapter and co-sponsored by the IEEE Electronics Packaging Society (EPS). Since its inauguration in 1997, EPTC has been established as a highly-reputable, international electronics packaging conference and is the IEEE EPS flagship conference in the Asia and Pacific Region.

The 25th Electronics Packaging Technology Conference (EPTC2023) will take place from 5th to 8th December 2023 in Singapore. It will feature keynotes, technical sessions, invited talks, panels, workshops, exhibits, and networking activities. Topics include modules, components, materials, equipment technology, assembly, reliability, interconnect design, device and systems packaging, heterogeneous integration, wafer-level packaging, flexible electronics, LED, IoT, 5G/6G, emerging technologies, 2.5D/3D integration technologies, smart manufacturing, automation, and AI. This year marks the 25th anniversary of EPTC. The usual 3-day event will be extended to a 4-day event to celebrate the occasion.

Keynote Talks

- Topic:** Advanced System Integration Technology Trend
Speaker: Dr Douglas Yu, Vice President of TSMC R&D and TSMC Distinguished Fellow
- Topic:** 2.5D/3D Heterogeneous Integration for Silicon Photonics Engines
Speaker: Dr. Radha Nagarajan, Senior Vice President and Chief Technology Officer of Marvell's Optical and Copper Connectivity Group
- Topic:** Will Advanced Packaging Save Moore's Law?
Speaker: Dr. Yang Pan, Corporate Vice President, Lam Research.
- Topic:** Advanced Packages Enriching Heterogeneous Integration
Speaker: Dr. C.P. Hung, Vice President, Corporate R&D, ASE Group.

Technology Talk

- Topic:** Challenges in the Analysis and Testing of Advanced Packaging Systems
Speaker: Dr. Mo Shakouri, co-founder, President & CEO, Microsanj LLC.

Panel Sessions

- Topic:** - Chiplet Integration
Moderator:
 - Dr. Jiantao, Zheng, Huawei**Panellists:**
 - Dr. Ravi Mahajan, Intel Fellow and Director of Pathfinding for Assembly and Packaging technologies, Intel;
 - Dr. Arvind Sundarajan, Managing Director/Head of Applied Packaging Development Center, Applied Materials;
 - Dr. Surya Bhattacharya, Director of SiP, IME, A-Star;
- Topic:** - Artificial Intelligence for Package Design and Manufacturing
Moderator:
 - Dr. Sam Karikalan, Broadcom, Inc., VP of Conferences - IEEE EPS**Panellists:**
 - Dr. Byung Joon Han, CEO, Silicon Box, Singapore;
 - Ms. Grace O'Malley, VP Technical and Project Operations, iNEMI;

- Mr. Vincent DiCaprio, VP, Applied Materials;
- Prof. Kuo Ning Chiang, National Tsing Hua University

Invited Talks

1. Development of Novel Polymer Materials for Advanced Packaging, **Takenori Fujiwara, Toray**
2. Water-to-Wafer and Die-to-Wafer Hybrid Bonding for Advanced Interconnects, **V. Dragoi, EV Group**
3. Forward-Looking Roadmap View to Enable Heterogeneous Integration, **G. Refai-Ahmed, AMD**
4. Fluxless Bonding For Higher Density and Bandwidth Packages, **Steve Ng, Kulicke & Soffa**
5. The Era of Generative AI and Advanced Packaging, **Chak Wing Kei, Tommy, ASMPT**

PDCs

1. Fan-Out, Chiplet, and Heterogeneous Integration Packaging by John H Lau
2. Flip Chip Interconnect by Eric Perfecto
3. Co-Packaged Si Photonics: Opportunities and Challenges by Amr S. Helmy
4. Design-on-Simulation Technology for Advanced Packaging Reliability Life Prediction by Professor K. N. Chiang
5. Automotive Electronics Reliability – Challenges and Opportunities by Pradeep Lall

Conference Venue:

Grand Copthorne Waterfront Hotel, Singapore

Conference Registration Schedule

Author Registration	September 15, 2023
Early Bird Registration	October 31, 2023
Standard Registration	December 5, 2023

Please [click here](#) for conference registration;

Conference hotel booking, please [click here](#)

Please check the [conference website](#) for the latest updates.